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Zytel® HTNWRF51G30 NC010 (PRELIMINARY)

HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTNWRF51G30 NC010 is a 30% Glass Reinforced, PPA, Teflon® Lubricated, High Performance Polyamide with Low Wear and Low Friction

Product information

Resin Identification Part Marking Code ISO designation	PA6T/XT-GF30SD >PA6T/XT-GF30SD< ISO 16396-PA6T/XT,GF30,M1GHNRS,S10-100		ISO 1043 ISO 11469 I0-100
Rheological properties	dry/cond.		
Moulding shrinkage, parallel Moulding shrinkage, normal	0.2/- 0.7/-	% %	ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties	dry/cond.		
Tensile Modulus Stress at break Strain at break Flexural Modulus Charpy impact strength, 23°C Charpy notched impact strength, 23°C Charpy notched impact strength, -30°C Poisson's ratio	10000/10000 190/173 2.6/2.2 9300/- 65/- 11/- 9/- 0.34/0.34	MPa MPa % MPa kJ/m² kJ/m² kJ/m²	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 179/1eU ISO 179/1eA ISO 179/1eA
Tribological properties	dry/cond.		
Coefficient of sliding friction, 1h against steel	-/0.25		ASTM 1894
Thermal properties	dry/cond.		
Melting temperature, 10°C/min Temp. of deflection under load, 1.8 MPa CLTE, Parallel, -40-23°C Coeff. of linear therm. expansion, parallel CLTE, Normal, -40-23°C Coeff. of linear therm. expansion, normal Thermal conductivity of melt Spec. heat capacity of melt	300/* 260/* 16/* 15/* 53/* 60/* 0.23 1740	°C °C E-6/K E-6/K E-6/K W/(m K) J/(kg K)	ISO 11357-1/-3 ISO 75-1/-2 ISO 11359-1/-2 ISO 11359-1/-2 ISO 11359-1/-2 ISO 11359-1/-2
Flammability			
FMVSS Class	DN	DNI ISO 37	

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Electrical properties	dry/cond.		
Comparative tracking index	550/-	IEC 60112	
Other properties	dry/cond.		
Density	1560/- kg/m³	ISO 1183	
Density of melt	1350 kg/m³		
Injection			
Drying Recommended	yes		
Drying Temperature	100 °C		
Drying Time, Dehumidified Dryer	6-8 h		
Processing Moisture Content	≤0.1 %		
Melt Temperature Optimum	325 °C		
Min. melt temperature	320 °C		
Max. melt temperature	330 °C		
Mold Temperature Optimum	150 °C		
Min. mould temperature	140 °C		
Max. mould temperature	180 °C		
Characteristics			

Additives

Release agent

Additional Information

Injection molding

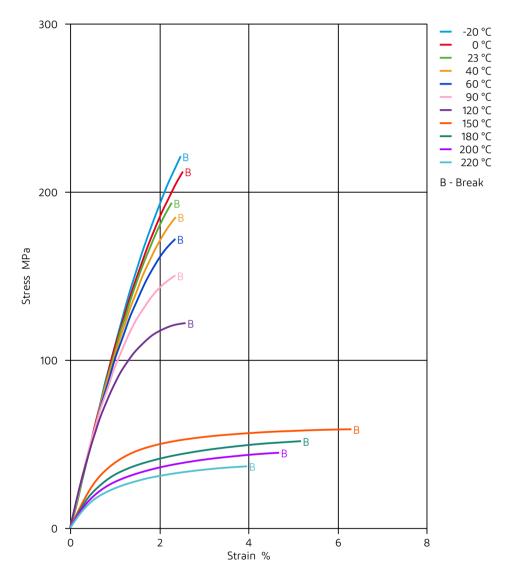
During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the hold up time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE.

When lower mold temperatures are used, the initial warpage and shrinkage may be lower, but the surface appearance and chemical resistance may be reduced, and the dimensional change may be greater when parts are subsequently heated.



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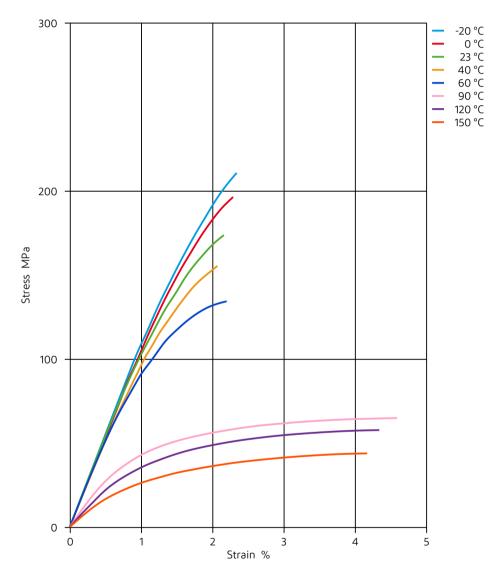
Stress-strain (dry)





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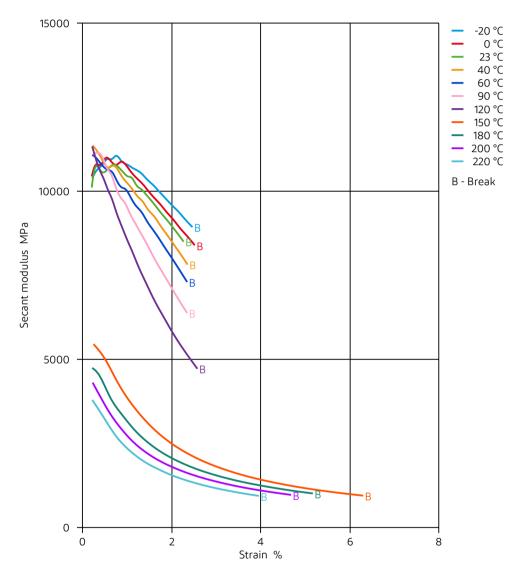
Stress-strain (cond.)





HIGH PERFORMANCE POLYAMIDE RESIN

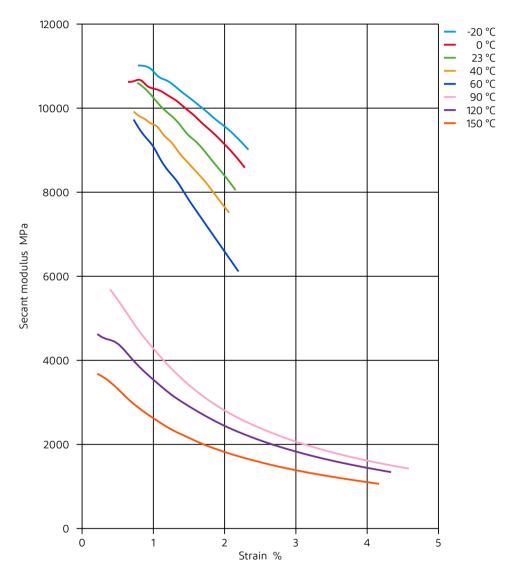
Secant modulus-strain (dry)





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Secant modulus-strain (cond.)



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Page: 6 of 6

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The above data are preliminary and are subject to change as additional data are developed on subsequent lots.

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